That which is claimed is:

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- 1. An energy-ray curing resin composition comprising a photopolymerizable resin component which can be cured by irradiation with an energy ray, a photopolymerization initiator component which makes it possible to cure said photopolymerizable resin component with irradiation of an energy ray, and a curing agent component capable of curing at least one of said photopolymerizable resin components without irradiation of an energy ray.
- 2. The energy-ray curing resin composition as described in claim 1, further comprising a curing SUB accelerator component which accelerates curing when curing at least one of said photopolymerizable resin components and said curing agent component without irradiation of an energy ray.
- 3. The energy-ray curing resin composition as

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 described in claim 1 or 2, comprising an epoxy resin
 component having a cyclic ether structure in a

 20 molecular structure as the photopolymerizable resin
 component.
 - described in any of claims 1 to 3, comprising an acid anhydride or a derivative thereof as the curing agent component.

- 5. The energy-ray curing resin composition as described in any of claims 1 to 3, comprising monohydric or polyhydric alcohols as the curing agent component.
- 6. The energy-ray curing resin composition as described in claim 2 or 3, comprising an acid anhydride or a derivative thereof and monohydric or polyhydric alcohols as the curing agent component or the curing accelerator component.
 - 7. The energy-ray curing resin composition as described in any of claims 3 to 6, wherein the curing agent component or the curing accelerator component comprises a compound which can react with the epoxy resin component and which does not have a nitrogen atom in a molecular structure.

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- 8. The/energy-ray curing resin composition as

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 described in any of claims 3 to 7, comprising 3,4epoxycyclohexylmethyl-3,4-epoxycyclohexanecalboxylate
 as the photopolymerizable resin component.
- 9. The energy-ray curing resin composition as described in claim 4 or any of claims 6 to 8, comprising maleic anhydride or a derivative thereof as the acid anhydride or derivative thereof.
- SUB 10. The energy-ray curing resin composition $25^{1/2}$ as described in any of claims 5 to 0, comprising

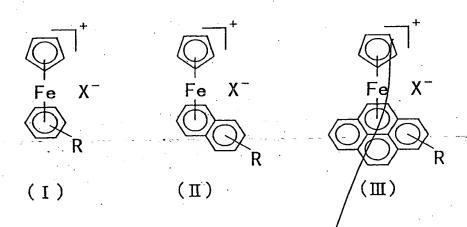
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polyethylene glycol as the alcohols.

- as described in any of claims 1 to 10, wherein the curing agent component is present with a proportion of 0.1 to 1.4 mol per mol of the photopolymerizable resin component which can react with the curing agent component.
- 12. The energy-ray curing resin composition as described in claim 2, 3 or any of claims 6 to 11, wherein the curing accelerator component is present with a proportion of 0.04 to 0.6 mol per mol of the curing agent component.
- 13. The energy-ray cyting resin composition as described in any of claims 1 to 12, comprising a cationic photopolymerization initiator component as the photopolymerization initiator component.
- 14. The energy-ray curing resin composition as described in any of claims 1 to 13, comprising an iron-allene base compound represented by the 20 following Formula (I), (II) or (III) as the photopolymerization initiator component:

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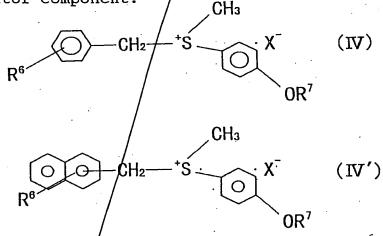
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wherein X represents BF4, PF6, As F6 or SbF6.

as described in any of claims 1 to 14, comprising a photo-thermopolymerization initiator which can initiate polymerization by both light and heat as the photopolymerization initiator component.

as described in any of claims 1 to 15, comprising a sulfonium salt represented by the following Formula (IV), (IV') or (V) as the photopolymerization initiator component:



25 in Formula (IV) or (IV') described above, R^6

represents hydrogen, hal ϕ gen, a nitro group or a methyl group; R^7 represents hydrogen, CH_3CO or CH_3OCO ; and X^- represents SbF_6^- , PF_6^- , AsF_6^- or BF_4^- ;

 $R^{1}0 - \begin{pmatrix} R^{2} & CH_{2} - \begin{pmatrix} X^{-} & Y \\ R^{3} & R^{4} \end{pmatrix} \end{pmatrix}$ (V)

in Formula (V) described above, R^1 represents hydrogen, a methyl group, an acetyl group or a methoxycarbonyl group; R^2 and R^3 represent

independently hydrogen, halogen or an alkyl group of C_1 to C_4 ; R^4 represents hydrogen, halogen or a methoxy group; R^5 represents an alkyl group of C_1 to C_4 ; and X^- represents SbF_6^- , PF_6^- , AsF_6^- or BF_4^- .

- 17. The energy-ray curing resin composition

 15 as described in any of claims 1 to 16, wherein the photopolymerization initiator component comprises a photopolymerization initiator comprising a binary or higher system containing a photopolymerization initiator and a photo-thermopolymerization initiator.
- 20 18. The energy-ray curing resin composition as described in claim 17, wherein the polymerization 50% initiator component comprising the binary or higher system contains at least one of aryl base sulfonium salts or the iron-allene base compounds represented 25 by Formula (I), (II) or (III) as the

photopolymerization initiator and at least one of the sulfonium salts represented by Formula (IV), (IV') or (V) as the photo-thermopolymerization initiator.

- 19. The energy-ray curing resin composition

 5 as described in claim 17 or 18, wherein the
 polymerization initiator component comprising the
 binary or higher system contains the photothermopolymerization initiator in a proportion of 10
 to 100 % by weight.
 - as described in any of claims 1 to 19, wherein the photopolymerization initiator component is contained in a proportion of 0.1 to 6.0 parts by weight per 100 parts by weight of the total weight of the components excluding the photopolymerization initiator component.
 - 21. An energy-ray curing resin-molded article obtained by curing the energy-ray curing resin composition as described in any of claims 1 to 20.
 - 22. A paste material comprising the energy20 ray curing resin composition as described in any of claims 1 to 20.
 - 23. A composite molding material comprising the energy-ray curing resin composition as described in any of claims 1 to 20.
 - 25 24. An adhesive comprising the energy-ray

curing resin composition as described in any of claims 1 to 20.

25. A coating material comprising the energy-ray curing resin composition as described in any of claims 1 to 20.

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